

SEMICONDUCTOR PACKAGE AND METHOD THEREFOR

Abstract of the Disclosure

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A semiconductor package substrate (10) has an array of package sites (13,14,16,21,22, and 23) that are substantially identical. The entire array of package sites (13,14,16,21,22, and 23) is covered by an encapsulant (19). The individual package sites (13,14,16,21,22, and 23) are singulated by sawing through the encapsulant (19) and the underlying semiconductor package substrate (10).

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